

## Dotted box > PCB manufacturer info

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

### BOARD CHARACTERISTICS

Copper Layer Count: 2

Board Thickness: 1.6000 mm

Board overall dimensions: 19.0500 mm x 50.7951 mm

Min track/spacing: 0.0000 mm / 0.2540 mm

Min hole diameter: 0.3000 mm

Copper Finish: HASL

Impedance Control: No

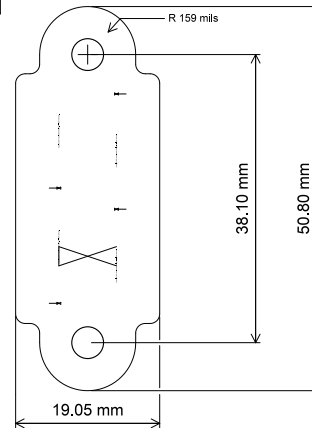
Castellated pads: No

Plated Board Edge: No

Edge card connectors: No

Outer Copper Weight: 1 oz

Via type: Tented



### NOTES

- 1.Layers: 2
- 2.Thickness: 1.6
- 3.Surface finish: HASL
- 4.Outer Copper Weight: 1oz
- 5.Via covering: Tented
- 6.Min hole size: .3mm
- 7.Gold Fingers: No
- 8.Castellated Holes: No
- 9.Edge Plating: No

### LAYERS

User.1

Edge.Cuts



Sheet:  
File: TEE-CAN.kicad\_pcb

### Title:

Size: A4  
KiCad E.D.A. 8.0.2-1

Date:

Rev:  
Page: 1/1